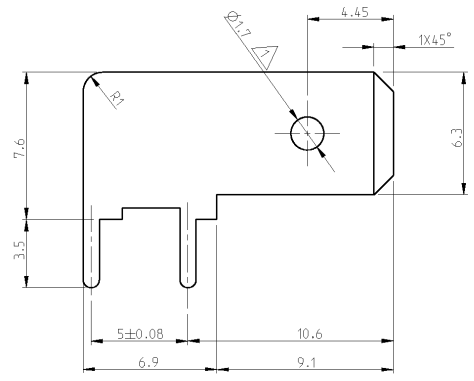
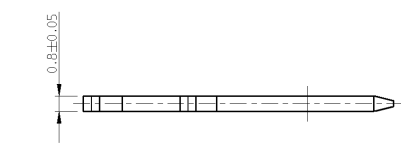


THIS DRAWING IS UNPUBLISHED.
 RELEASED FOR PUBLICATION
 BY - ALL RIGHTS RESERVED.

LOC	DIST	REVISIONS				
P	LTR	DESCRIPTION	DATE	DWN	APVD	
A1	-					
	A2	REVISED PER ECO-11-005301	13APR11	RK	HMR	

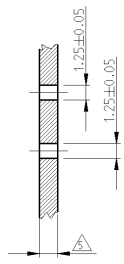
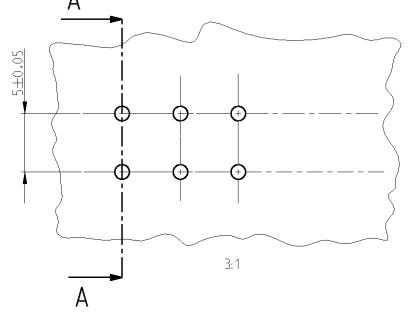


- NOTES/BEMERKUNG
- 1 AUSFÜHRUNG 928814-4/-5/-6 OHNE LOCH
EXECUTION 928814-4/-5/-6 WITHOUT HOLE
 - 2 3-7 µm Sn ÜBER 0.8 -1.5 µm Ni
3-7 µm Sn OVER 0.8-1.5 µm Ni
 - 3 4-8 µm Sn
4-8 µm Sn
 - 4 ANLIEFERUNGSZUSTAND: EINZELWARE IN VERSANDKARTON
DELIVERED STATE: LOOSE PIECE IN CORRUGATED SHIPPING BOX
 - 5 LEITERPLATTENDICKE NACH EN 60249-2-4. TABELLE 3
PCB-THICKNESS TO EN 60249-2-4. TABLE 3
 - 6 **OBSELETE**



SCALE 1:1

EMPFOLHENES LEITERPLATTEN LOCHBILD
 RECOMMENDED PCB HOLE PATTERN



FINISH	MATERIAL	PART NO	REV
1	BLANK	Cu Zn 30	4
2	BLANK	Cu Zn 30	4
3	BLANK	Cu Zn 30	4
4	BLANK	Cu Zn 30	4
5	BLANK	Cu Zn 30	4
6	BLANK	Cu Zn 30	4

DIMENSIONS: mm		TOLERANCES UNLESS OTHERWISE SPECIFIED: ±0.2		DWN Dhanesh 06-Sep-07		CHK W. Hoffman 04-Okt-07		APVD Gerlach		NAME		TE Connectivity			
MATERIAL SEE TABLE		FINISH SEE TABLE		PRODUCT SPEC		APPLICATION SPEC		WEIGHT		SIZE A3		DRAWING NO C-928814			
CUSTOMER DRAWING										SCALE 2:1		SHEET 1 OF 1		REV A2	

AMP 1470-19 REV 31MAR2000

Prof/ENGINEER DRAWING